

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

TSSOP Exp. Pad

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**TOTAL MASS (g) : 0.05412**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002047	1000000	37823.4921875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.014625	975000	270233.78125		
		Iron (Fe)	7439-89-6	0.000360	24000	6651.90869141		
		Phosphorus (P)	7723-14-0	0.000004	300	73.9100952148		
		Zinc (Zn)	7440-66-6	0.000010	700	184.775222778		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.014999</b>	<b>1000000</b>	<b>277144.375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002064	1000000	38134.0234375		
		<b>External Plating Total:</b>				<b>0.002064</b>	<b>1000000</b>	<b>38134.0234375</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001037	1000000	19161.1914062		
<b>Internal Plating Total:</b>				<b>0.001037</b>	<b>1000000</b>	<b>19161.1914062</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000701	750000	12952.7441406		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000234	250000	4323.74072266		
<b>Die Attach Total:</b>				<b>0.000935</b>	<b>1000000</b>	<b>17276.484375</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004875	150000	90077.9296875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.026650	820000	492426		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000813	25000	15022.2265625		
		Carbon Black (C)	1333-86-4	0.000163	5000	3011.83642578		
		<b>Encapsulation Total:</b>				<b>0.032501</b>	<b>1000000</b>	<b>600538</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000537	1000000	9922.4296875		
					<b>TOTAL MASS (g) :</b>	<b>0.05412</b>		